

	Type	Hits	Search Text	DBs
1	BRS	71	("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and grid adj array and multi\$3 near (contact or terminal or pad)	USPAT; JPO
2	BRS	344	("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and multi\$3 near (contact or terminal or pad)	USPAT; JPO
3	BRS	51	("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and ((multi\$3 near layers) near (contact or terminal or pad))	USPAT; JPO
4	BRS	6	("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and ((multi\$3 near layers) near (bump))	USPAT; JPO
5	BRS	0	("chip on chip" or stack\$3 near (chip or die or IC or semiconductor)) and ((multi\$3 near layers) near (bump))	USPAT; JPO
6	BRS	4	("chip on chip" or stack\$3 near (chip or die or IC or semiconductor)) and layers near (bump)	USPAT; JPO
7	BRS	6	("chip on chip" or stack\$3 near (chip or die or IC or semiconductor)) and (layers or coat\$3) near (bump)	USPAT; JPO
8	BRS	157	("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and multi\$3 near (contact or terminal or pad)	USPAT

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9	BRS	344	("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and multi\$3 near (contact or terminal or pad)	USPAT; JPO
10	BRS	23	("chip on chip" or (stack\$3 near (chip or die or IC or semiconductor))) and coat\$3 near (contact or terminal or pad)	USPAT; JPO
11	BRS	17	("chip on chip" or (stack\$3 near (chip or die or IC or semiconductor))) and coat\$3 near (contact or terminal or bump)	USPAT; JPO
12	BRS	12	"4032058"	USPAT; JPO
13	BRS	46	("chip on chip" or (stack\$3 near (chip or die or IC or semiconductor))) and (coat\$3 or cover) near (contact or terminal or bump or ball)	USPAT; JPO
14	BRS	46	("chip on chip" or (stack\$3 near (chip or die or IC or semiconductor))) and (coat\$3 or cover) near (contact or terminal or bump or ball)	USPAT; JPO
15	BRS	396	("chip on chip" or (stack\$3 near (chip or die or IC or semiconductor))) and (coat\$3 or cover or layers) near (contact or terminal or bump or ball)	USPAT; JPO
16	BRS	46	("chip on chip" or (stack\$3 near (chip or die or IC or semiconductor))) and (coat\$3 or cover) near (contact or terminal or bump or ball)	USPAT; JPO
17	BRS	1	"3392442".PN.	USPAT
18	BRS	1	"3436818".PN.	USPAT
19	BRS	1	"3486223".PN.	USPAT
20	BRS	1	"4617730".PN.	USPAT

	Type	Hits	Search Text	DBs
21	BRS	1	"5007163".PN.	USPAT
22	BRS	1	"5075965".PN.	USPAT
23	BRS	1	"5203075".PN.	USPAT
24	BRS	47	"5007163"	USPAT; JPO
25	BRS	46	"5075965"	USPAT; JPO
26	BRS	28	"5075965" and (tin or Sn)	USPAT; JPO
27	BRS	1	"6268739" and (tin or Sn)	USPAT; JPO
28	BRS	2	"6166556" and (tin or Sn)	USPAT; JPO
29	BRS	1166	257/777 and (contact or terminal or bump or ball or pad)	USPAT; JPO
30	BRS	204	257/777 and (layers or films or coat\$3 or cover or cap) near (contact or terminal or bump or ball or pad)	USPAT; JPO
31	BRS	65	257/777 and (layers or films or coat\$3 or cover or cap) near (contact or terminal or bump or ball or pad) and (tin or "Sn")	USPAT; JPO
32	BRS	23	"4369458"	USPAT; JPO
33	BRS	19	"5461261"	USPAT; JPO
34	BRS	24	"5796591"	USPAT; JPO
35	BRS	136	copper near melting adj point	USPAT; JPO
36	BRS	13	pure adj copper near melting adj point	USPAT; JPO
37	BRS	59	("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and (coat\$3 or cover or cap\$4 or layers) near (contact or terminal or pad)	JPO

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38	BRS	8	04088645.pn. or 6137184.pn. or 6133637.pn. or 6268739.pn. or 6166556.pn. or 6337522.pn. or 5796591.pn. or 5646828.pn.	USPAT; JPO
39	BRS	8	04088645.pn. or 6137184.pn. or 6133637.pn. or 6268739.pn. or 6166556.pn. or 6337522.pn. or 5796591.pn. or 5646828.pn.	USPAT; JPO
40	BRS	337	(257/777 or 361/760 or 438/108 or 438/109) and ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and (coat\$3 or cover or cap\$4 or layers) near (contact or terminal or pad or ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
41	BRS	319	(257/778 or 257/779 or 257/780 or 257/781) and ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and (coat\$3 or cover or cap\$4 or layers) near (contact or terminal or pad or ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
42	BRS	260	(257/723 or 257/724 or 257/685 or 257/686) and ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and (coat\$3 or cover or cap\$4 or layers) near (contact or terminal or pad or ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
43	BRS	208	(257/690 or 257/700) and ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and (coat\$3 or cover or cap\$4 or layers) near (contact or terminal or pad or ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB